Title (en)
  Method to pattern substrates

Title (de)
  Verfahren zur Strukturierung von Substraten

Title (fr)
  Procédé pour former des motifs sur des substrats

Publication
  EP 2881977 A2 20150610 (EN)

Application
  EP 14196320 A 20141204

Priority
  • EP 13195678 A 20131204
  • EP 14196320 A 20141204

Abstract (en)
  A method for creating a pattern on a substrate (10 1) is presented, the method comprises: providing a substrate (101) comprising silicon; creating
  a sacrificial layer (102) on the substrate (10 1), wherein the sacrificial layer is formed on a first surface area (101a) of the substrate thereby leaving
  a second surface area (101b) exposed; depositing a first functional layer (103) at least on the second surface area (101b) of the substrate (101);
  removing the sacrificial layer (102); characterized in that: removing the sacrificial layer (102) is performed by etching the sacrificial layer (102) with
  an acidic aqueous solution which does not adversely affect the first functional layer (103) and the substrate (10 1).

IPC 8 full level
  H01L 21/32 (2006.01); **B01L 3/00** (2006.01); **G01N 33/487** (2006.01); **G01N 33/543** (2006.01)

CPC (source: EP US)
  B81C 1/00206 (2013.01 - EP US); **B82Y 40/00** (2013.01 - US); **G01N 33/487** (2013.01 - EP US); **H01L 21/3085** (2013.01 - US);
  H01L 21/3086 (2013.01 - US); **H01L 21/32** (2013.01 - EP US); **H01L 21/32051** (2013.01 - US); **H01L 29/06** (2013.01 - US);
  B81B 2207/056 (2013.01 - EP US)

Citation (applicant)
  JACKSON, B.L.; GROVES, J.: "Hybrid Protein-lipid patterns form aluminum templates", LANGMUIR, vol. 23, no. 4, 2007, pages 2052 - 2057

Cited by
  KR20210135293A; US2022186362A1; US11788185B2; WO2020184284A1

Designated contracting state (EPC)
  AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
  BA ME

DOCDB simple family (publication)
  EP 2881977 A2 20150610; **EP 2881977 A3 20151014**; **EP 2881977 B1 20190828**; US 2015155179 A1 20150604; US 9373519 B2 20160621

DOCDB simple family (application)
  EP 14196320 A 20141204; US 201414560202 A 20141204